BROADCOM®

Data Sheet

HCPL-7723/0723

50-MBd 2-ns PWD High-Speed CMOS Optocoupler

Description

Available in either 8-pin DIP or SO.8 package style respectively, the Broadcom® HCPL-7723 or HCPL-0723 optocoupler utilize the latest CMOS IC technology to achieve outstanding speed performance of minimum 50 MBd data rate and 2-ns maximum pulse width distortion.

Basic building blocks of HCPL-7723/0723 are a CMOS LED driver IC, a high speed LED and a CMOS detector IC. A CMOS logic input signal controls the LED driver IC, which supplies current to the LED. The detector IC incorporates an integrated photodiode, a high-speed transimpedance amplifier, and a voltage comparator with an output driver.

CAUTION! It is advised that normal static precautions be taken in handling and assembly of this component to prevent damage and/or degradation, which may be induced by ESD. The components featured in this data sheet are not to be used in military or aerospace applications or environments.

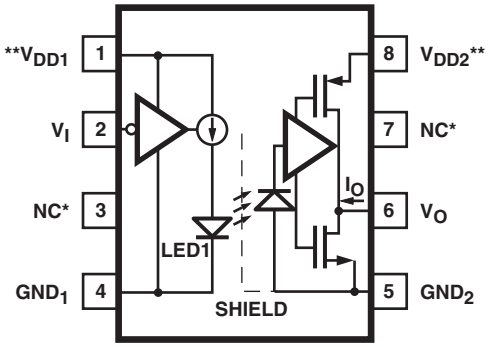
Features

- +5V CMOS compatibility
- High speed: 50 MBd min.
- 2-ns max. pulse width distortion
- 22-ns max. propagation delay
- 16 ns max. propagation delay skew
- 10 kV/µs min. common mode rejection
- –40 to 85°C temperature range
- Safety and regulatory approvals:
  - UL recognized:
    - 5000 V_{rms} for 1 min. per UL1577 for HCPL-7723 for option 020
    - 3750 V_{rms} for 1 min. per UL1577 for HCPL-0723
  - CSA component acceptance notice #5
  - IEC/EN/DIN EN 60747-5-5
    - V_{iorm} = 630 V_{peak} for HCPL-7723 option 060
    - V_{iorm} = 567 V_{peak} for HCPL-0723 option 060

Applications

- Digital fieldbus isolation: CC-Link, DeviceNet, Profibus, SDS, Isolated A/D or D/A conversion
- Multiplexed data transmission
- High-speed digital input/output
- Computer peripheral interface
- Microprocessor system interface

Functional Diagram



* PIN 3 IS THE ANODE OF THE INTERNAL LED AND MUST BE LEFT UNCONNECTED FOR GUARANTEED DATASHEET PERFORMANCE. PIN 7 IS NOT CONNECTED INTERNALLY.

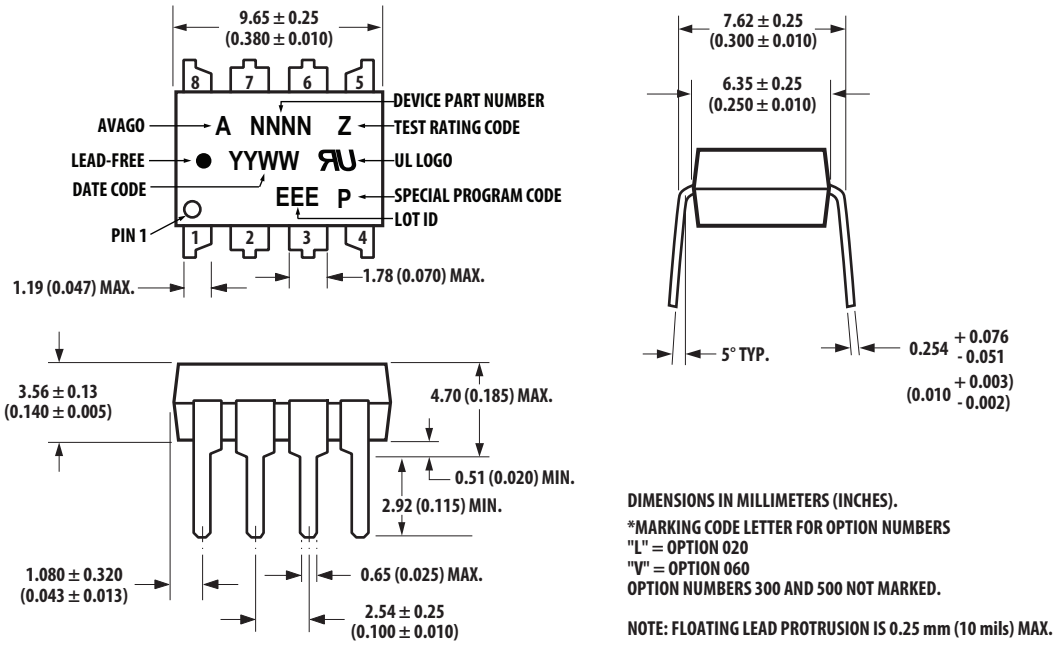
** A 0.01 to 0.1 µF BYPASS CAPACITOR MUST BE CONNECTED AS CLOSE AS POSSIBLE BETWEEN PINS 1 AND 4, AND 5 AND 8.

Truth Table

V_I Input	LED1	V_O Output
H	OFF	H
L	ON	L

Package Outline Drawings

HCPL-7723 8-Pin DIP Package

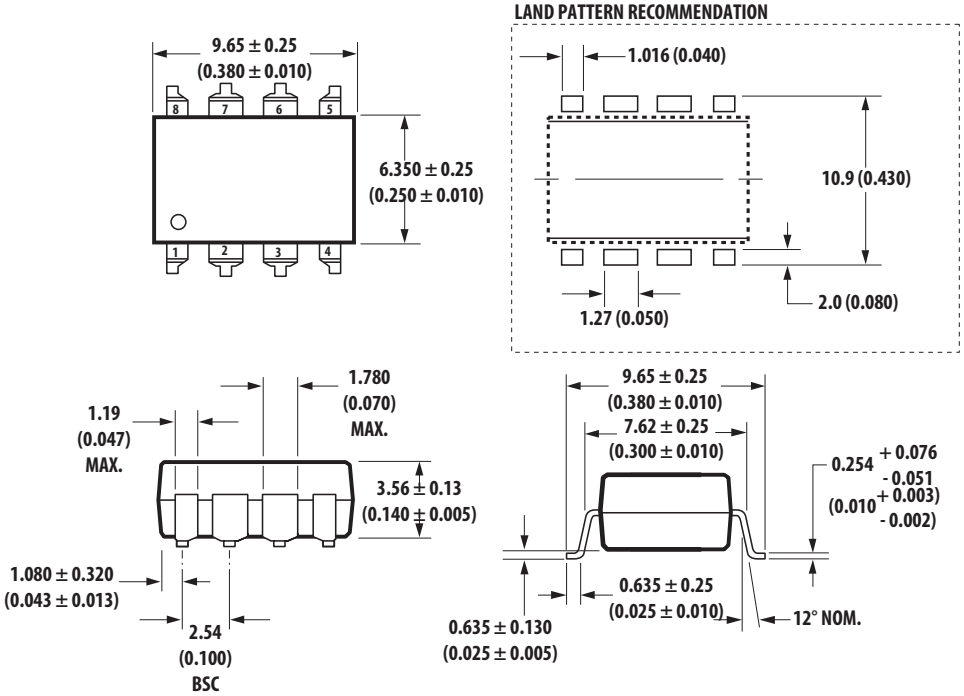


DIMENSIONS IN MILLIMETERS (INCHES).

*MARKING CODE LETTER FOR OPTION NUMBERS
"L" = OPTION 020
"V" = OPTION 060
OPTION NUMBERS 300 AND 500 NOT MARKED.

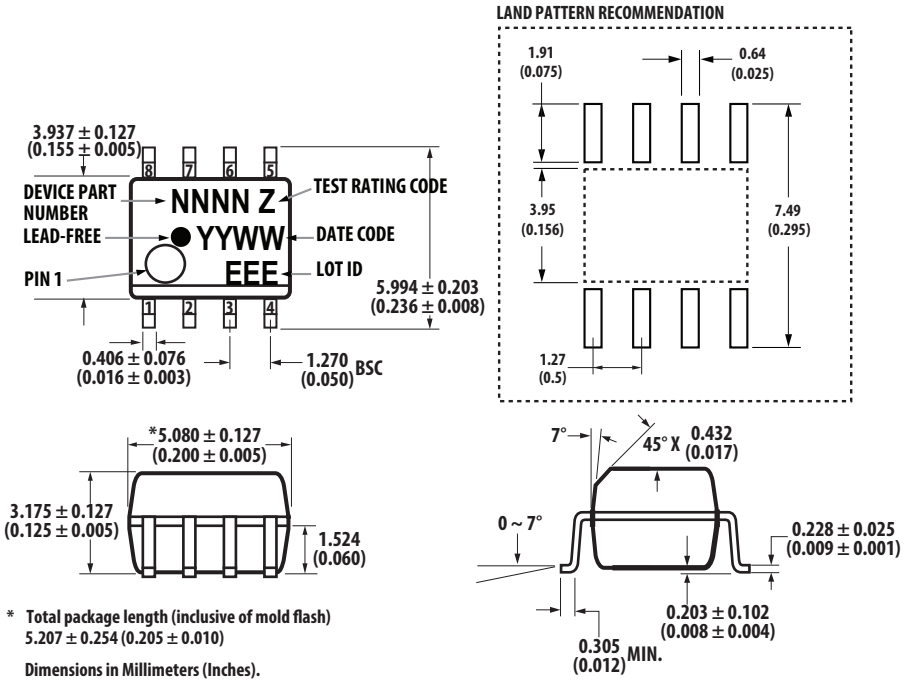
NOTE: FLOATING LEAD PROTRUSION IS 0.25 mm (10 mils) MAX.

HCPL-7723 Package with Gull Wing Surface Mount Option 300



DIMENSIONS IN MILLIMETERS (INCHES).
LEAD COPLANARITY = 0.10 mm (0.004 INCHES).
NOTE: FLOATING LEAD PROTRUSION IS 0.15 mm (6 mils) MAX.

HCPL-0723 Small Outline SO-8 Package



* Total package length (inclusive of mold flash)
5.207 ± 0.254 (0.205 ± 0.010)

Dimensions in Millimeters (Inches).
Note: Floating lead protrusion is 0.15 mm (6 mils) max.
Lead coplanarity = 0.10 mm (0.004 inches) max.
Option number 500 not marked.

Device Selection Guide

8-Pin DIP (300 mil)	Small Outline SO-8
HCPL-7723	HCPL-0723

Ordering Information

HCPL-0723 and HCPL-7723 are UL Recognized with 3750 Vrms for 1 minute per UL1577.

Part Number	Option		Package	Surface Mount	Gull Wing	Tape and Reel	UL5000 Vrms / 1 Minute Rating	IEC/EN/DIN EN 60747-5-5	Quantity
	RoHS Compliant	Non RoHS Compliant							
HCPL-7723	-000E	no option	300 mil DIP-8						50 per tube
	-300E	-300		X	X				50 per tube
	-500E	-500		X	X	X			1000 per reel
	-020E	-020					X		50 per tube
	-320E	-320		X	X		X		50 per tube
	-520E	-520		X	X	X	X		1000 per reel
	-060E	-060						X	50 per tube
	-360E	-360		X	X			X	50 per tube
	-560E	-560		X	X	X		X	1000 per reel
HCPL-0723	-000E	no option	SO-8	X					100 per tube
	-500E	-500		X		X			1500 per reel
	-060E	-060		X				X	100 per tube
	-560E	-560		X		X		X	1500 per reel

To order, choose a part number from the part number column and combine with the desired option from the option column to form an order entry.

Example 1:

HCPL-7723-560E to order product of Gull Wing Surface Mount package in Tape and Reel packaging with IEC/EN/DIN EN 60747-5-5 Safety Approval and RoHS compliant.

Example 2:

HCPL-0723 to order product of Small Outline SO-8 package in Tube packaging and non RoHS compliant.

Option data sheets are available. Contact your Broadcom sales representative or authorized distributor for information.

NOTE: The notation #XXX is used for existing products, while (new) products launched since July 15, 2001 and RoHS compliant will use –XXXE.

Regulatory Information

The HCPL-7723/0723 have been approved by the following organizations:

- **UL —** Recognized under UL1577, component recognition program, File E55361.
- **CSA —** Approval under CSA Component Acceptance Notice #5, File CA88324.
- **IEC/EN/DIN EN 60747-5-5 —** Approved with Maximum Working Insulation Voltage:
  - V_{iorm} = 567 V_{peak} for HCPL-0723
  - V_{iorm} = 630 V_{peak} for HCPL-7723

Solder Reflow Profile

Recommended reflow condition as per JEDEC Standard, J-STD-020 (latest revision). Non-Halide Flux should be used.

Insulation and Safety Related Specifications

Parameter	Symbol	Value		Unit	Conditions
		7723	0723		
Minimum External Air Gap (Clearance)	L(I01)	7.1	4.9	mm	Measured from input terminals to output terminals, shortest distance through air.
Minimum External Tracking (Creepage)	L(I02)	7.4	4.8	mm	Measured from input terminals to output terminals, shortest distance path along body.
Minimum Internal Plastic Gap (Internal Clearance)		0.08	0.08	mm	Insulation thickness between emitter and detector; also known as distance through insulation.
Tracking Resistance (Comparative Tracking Index)	CTI	≥175	≥175	V	DIN IEC 112/VDE 0303 Part 1.
Isolation Group		IIIa	IIIa		Material Group (DIN VDE 0110, 1/89, Table 1).

All Broadcom data sheets report the creepage and clearance inherent to the optocoupler component itself. These dimensions are needed as a starting point for the equipment designer when determining the circuit insulation requirements. However, once mounted on a printed circuit board, minimum creepage and clearance requirements must be met as specified for individual equipment standards. For creepage, the shortest distance path along the surface of a printed circuit board between the solder fillets of the input and output leads must be considered. There are recommended techniques such as grooves and ribs, which may be used on a printed circuit board to achieve desired creepage and clearances. Creepage and clearance distances will also change depending on factors such as pollution degree and insulation level.

IEC/EN/DIN EN 60747-5-5 Insulation Characteristics (Option 060)

Description	Symbol	Characteristic		Unit
		HCPL-7723	HCPL-0723	
Installation Classification per DIN VDE 0110/39, Table 1				
For Rated Mains Voltage ≤ 150V_{rms}		I – IV	I – IV	
For Rated Mains Voltage ≤ 300V_{rms}		I – III	I – III	
For Rated Mains Voltage ≤ 600V_{rms}		I – IV	I – III	
Climatic Classification		55/85/21	55/85/21	
Pollution Degree (DIN VDE 0110/39)		2	2	
Maximum Working Insulation Voltage	V_{IORM}	630	567	V_{peak}
Input to Output Test Voltage, Method b[a] V_{IORM} x 1.875 = V_{PR}, 100% Production Test with t_m = 1s, Partial Discharge < 5 pC	V_{PR}	1181	1063	V_{peak}
Input to Output Test Voltage, Method a[a] V_{IORM} x 1.6 = V_{PR}, Type and Sample Test, t_m = 10s, Partial Discharge < 5 pC	V_{PR}	1008	907	V_{peak}
Highest Allowable Overvoltage (Transient Overvoltage t_{ini} = 60s)	V_{IOTM}	8000	6000	V_{peak}
Safety-Limiting Values – Maximum Values Allowed in the Event of a Failure				
Case Temperature	T_S	175	150	°C
Input Current	$I_{S, INPUT}$	230	150	mA
Output Power	$P_{S, OUTPUT}$	600	600	mW
Insulation Resistance at T_S, V_{IO} = 500V	R_S	≥10^9	≥10^9	Ω

a. Refer to the optocoupler section of the Isolation and Control Component Designer's Catalog, under Product Safety Regulations section IEC/EN/DIN EN 60747-5-5, for a detailed description of Method a and Method b partial discharge test profiles.

NOTE: These optocouplers are suitable for safe electrical isolation only within the safety limit data. Maintenance of the safety data is ensured by means of protective circuits.

Absolute Maximum Ratings

Parameter	Symbol	Min.	Max.	Unit
Storage Temperature	T_S	–55	125	°C
Ambient Operating Temperature[a]	T_A	–40	85	°C
Supply Voltages	V_{DD1}, V_{DD2}	0	6.0	V
Input Voltage	V_I	–0.5	V_{DD1} + 0.5	V
Output Voltage	V_O	–0.5	V_{DD2} + 0.5	V
Average Output Current	I_O	—	10	mA
Lead Solder Temperature	260°C for 10 sec., 1.6 mm below seating plane.			
Solder Reflow Temperature Profile	See Solder Reflow Profile section.			

a. Absolute maximum ambient operating temperature means the device will not be damaged if operated under these conditions. It does not guarantee functionality

Recommended Operating Conditions

Parameter	Symbol	Min.	Max.	Unit
Ambient Operating Temperature	T_A	–40	85	°C
Supply Voltages	V_{DD1}, V_{DD2}	4.5	5.5	V
Logic High Input Voltage	V_{IH}	2.0	V_{DD1}	V
Logic Low Input Voltage	V_{IL}	0.0	0.8	V
Input Signal Rise and Fall Times	t_{ir}, t_{if}	—	1.0	ms

Electrical Specifications

Test conditions that are not specified can be anywhere within the recommended operating range.

All typical specifications are at T_A = +25°C, V_{DD1} = V_{DD2} = +5V.

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Logic Low Input Supply Current[a]	I_{DD1L}	—	8.4	10	mA	V_I = 0V; Figure 1
Logic High Input Supply Current[a]	I_{DD1H}	—	0.6	3	mA	V_I = V_{DD1}; Figure 2
Output Supply Current	I_{DD2L}	—	2.1	5	mA	Figure 3
	I_{DD2H}	—	2.0	5	mA	Figure 4
Input Current	I_I	–10	—	10	µA	
Logic High Output Voltage	V_{OH}	4.4	5.0	—	V	I_O = –20 µA, V_I = V_{IH}
		4.0	4.8	—	V	I_O = –4 mA, V_I = V_{IH}
Logic Low Output Voltage	V_{OL}	—	0	0.1	V	I_O = 20 µA, V_I = V_{IL}
		—	0.5	1.0	V	I_O = 4 mA, V_I = V_{IL}

a. The LED is ON when V_I is low and OFF when V_I is high.

Switching Specifications

Test conditions that are not specified can be anywhere within the recommended operating range.

All typical specifications are at T_A = +25°C, V_{DD1} = V_{DD2} = +5V.

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Propagation Delay Time to Logic Low Output[a]	t_{PHL}	—	16	22	ns	C_L = 15 pF CMOS Signal Levels; Figure 5
Propagation Delay Time to Logic High Output[a]	t_{PLH}	—	16	22	ns	C_L = 15 pF CMOS Signal Levels; Figure 5
Pulse Width	PW	20	—	—	ns	C_L = 15 pF CMOS Signal Levels
Maximum Data Rate		50	—	—	MBd	C_L = 15 pF CMOS Signal Levels
Pulse Width Distortion[b] |tPHL - tPLH|	|PWD|	—	1	2	ns	C_L = 15 pF CMOS Signal Levels; Figure 6
Propagation Delay Skew[c]	t_{PSK}	—	—	16	ns	C_L = 15 pF CMOS Signal Levels
Output Rise Time (10% to 90%)	t_R	—	8	—	ns	C_L = 15 pF CMOS Signal Levels
Output Fall Time (90% to 10%)	t_F	—	6	—	ns	C_L = 15 pF CMOS Signal Levels
Common Mode Transient Immunity at Logic High Output[d]	$\|CM_H\|$	10	15	—	kV/µs	V_{CM} = 1000V, T_A = 25°C, V_I = V_{DD1}, V_O > 0.8 V_{DD2}
Common Mode Transient Immunity at Logic Low Output[d]	$\|CM_L\|$	10	15	—	kV/µs	V_{CM} = 1000V, T_A = 25°C, V_I = 0V, V_O < 0.8V

a. t_{PHL} propagation delay is measured from the 50% level on the falling edge of the V_I signal to the 50% level of the falling edge of the V_O signal. t_{PLH} propagation delay is measured from the 50% level on the rising edge of the V_I signal to the 50% level of the rising edge of the V_O signal.

b. PWD is defined as $|t_{PHL} - t_{PLH}|$. %PWD (percent pulse width distortion) is equal to the PWD divided by pulse width.

c. t_{PSK} is equal to the magnitude of the worst-case difference in t_{PHL} and/or t_{PLH} that will be seen between units at any given temperature within the recommended operating conditions.

d. CM_H is the maximum common mode voltage slew rate that can be sustained while maintaining V_O > 0.8V_{DD2}. CM_L is the maximum common mode voltage slew rate that can be sustained while maintaining V_O < 0.8V. The common mode voltage slew rates apply to both rising and falling common mode voltage edges.

Package Characteristics

All typical specifications are at T_A = 25°C.

Parameter		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Input-Output Momentary Withstand Voltage[a, b, c]	–7723	V_{ISO}	3750	—	—	V_{rms}	RH ≤ 50%, t = 1 min, T_A = 25°C
	Option 020		5000	—	—		
	–0723		3750	—	—		
Input-Output Resistance[a]		R_{I-O}	—	10^{12}	—	Ω	V_{I-O} = 500 Vdc
Input-Output Capacitance		C_{I-O}	—	0.6	—	pF	f = 1 MHz
Input Capacitance[d]		C_I	—	3.0	—	pF	
Input IC Junction-to-Case Thermal Resistance	–7723	θ_{jci}	—	145	—	°C/W	Thermocouple located at center underside of package
	–0723		—	160	—		
Output IC Junction-to-Case Thermal Resistance	–7723	θ_{jco}	—	145	—	°C/W	
	–0723		—	135	—		
Package Power Dissipation		P_{PD}	—	—	150	mW	

a. Device considered a two-terminal device: pins 1, 2, 3, and 4 shorted together and pins 5, 6, 7, and 8 shorted together.

b. In accordance with UL1577, each HCPL-0723 is proof tested by applying an insulation test voltage≥ 4500 V_{rms} for 1 second (leakage detection current limit, I_{I-O} ≤ 5 µA). Each HCPL-7723 is proof tested by applying an insulation test voltage ≥ 4500 V_{rms} for 1 second (leakage detection current limit. I_{I-O} ≤ 5 µA.)

c. The Input-Output Momentary Withstand Voltage is a dielectric voltage rating that should not be interpreted as an input-output continuous voltage rating. For the continuous voltage rating, refer to your equipment level safety specification or Broadcom Application Note 1074, Optocoupler Input-Output Endurance Voltage.

d. C_I is the capacitance measured at pin 2 (V_I).

Figure 1: Typical Logic Low Input Supply Current vs. Temperature

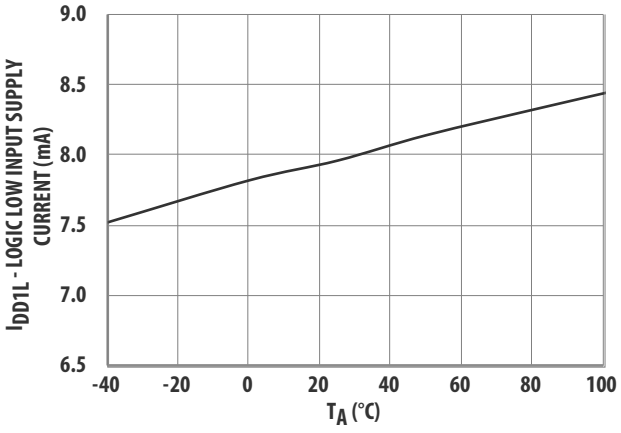


Figure 2: Typical Logic High Input Supply Current vs. Temperature

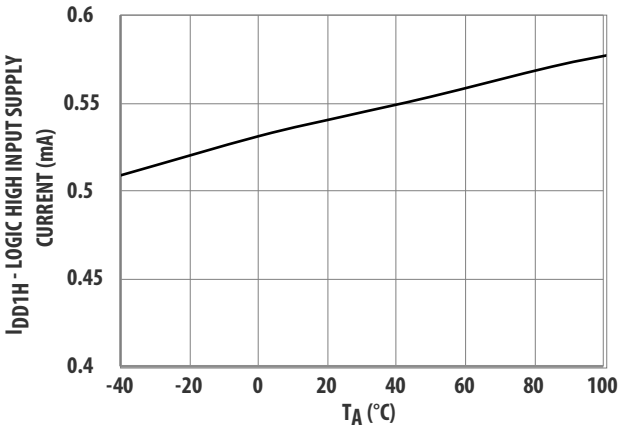


Figure 3: Typical Logic Low Output Supply Current vs. Temperature

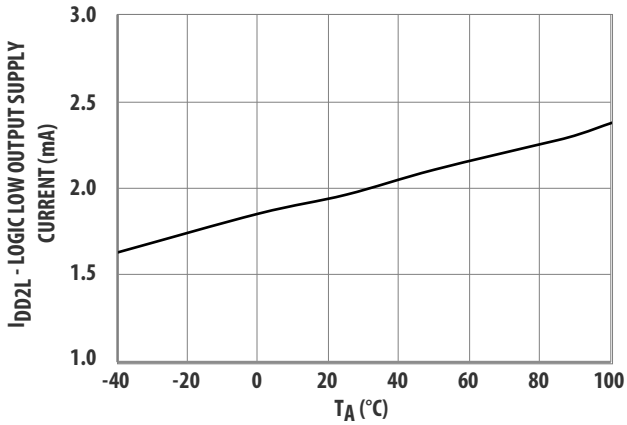


Figure 4: Typical Logic High Output Supply Current vs. Temperature

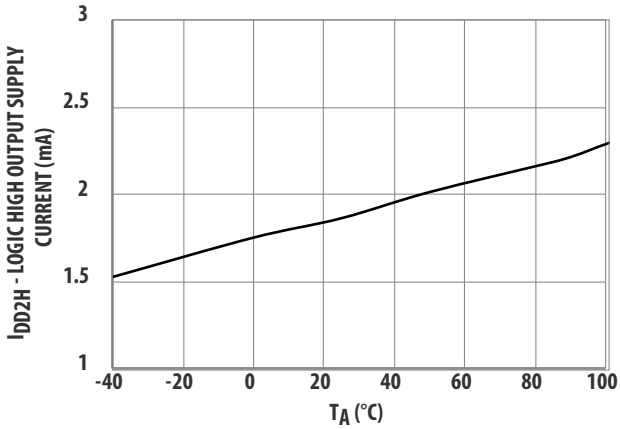


Figure 5: Typical Propagation Delay vs. Temperature

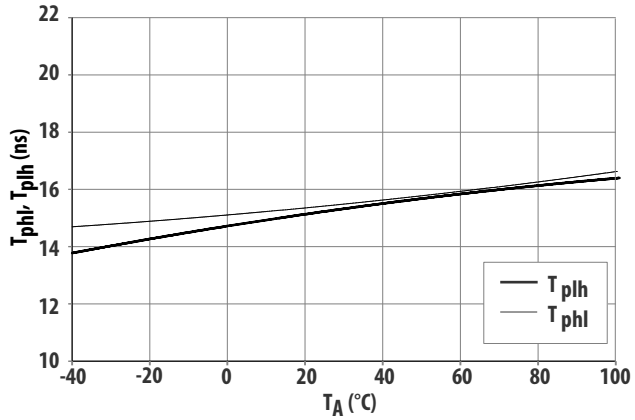
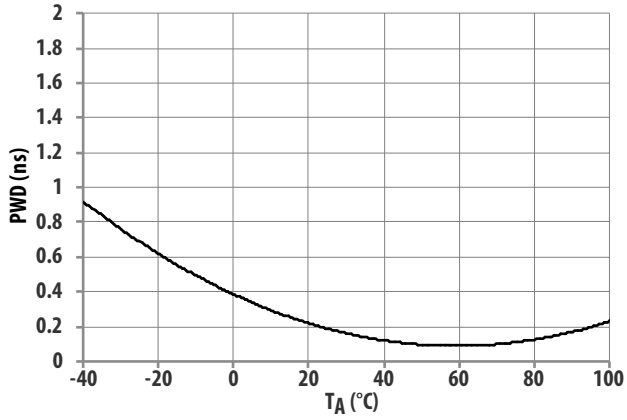


Figure 6: Typical Pulse Width Distortion vs. Temperature



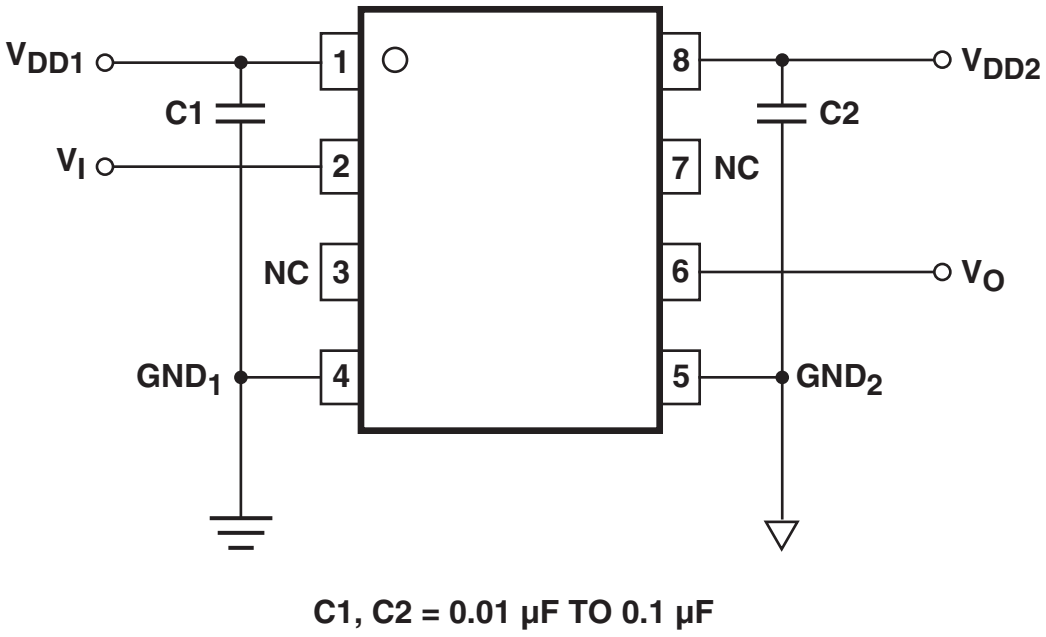
Application Information

Bypassing and PC Board Layout

The HCPL-7723/0723 optocouplers are extremely easy to use. No external interface circuitry is required because the HCPL-7723/0723 use high-speed CMOS IC technology allowing CMOS logic to be connected directly to the inputs and outputs.

As shown in Figure 7, the only external components required for proper operation are two bypass capacitors. Capacitor values should be between 0.01 µF and 0.1 µF. Each capacitor should be placed as close as possible to the input and output power-supply pins of the optocoupler.

Figure 7: Functional Diagram



C1, C2 = 0.01 µF TO 0.1 µF

BROADCOM®

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